

V9

No Clean Solder Paste

NO VOIDS ARE THE BEST VOIDS



NEW

KEY FEATURES

- Low to no voiding; <1% on BGA and <5% on BTC components
- REACH and RoHS compliant
- Consistent print volume on area ratios < 0.66
- Clear, pin-testable, and high reliability residues
- Stable print performance 12+ hours
- Available in SAC305 T4

LOOKING TO ELIMINATE VOIDS?

V9 is capable of ultra-low/no voiding on BTC components without vacuum reflow.

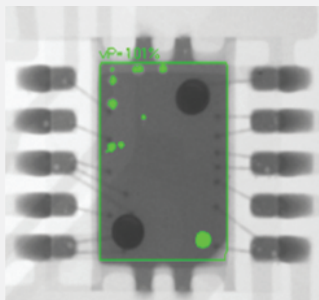
V9 low-voiding no clean solder paste is specifically engineered to minimize voiding on all component types including QFN, LGA, BGA, D-PAK and other void sensitive components without vacuum reflow. V9 reduces voiding to 1% on BGAs and <5% on BTCs while providing stable performance on ultra-fine pitch printing at area ratios <0.66 over 12 hours. Its residues are clear, easily pin-testable and have high SIR properties ideal for high reliability applications. V9 low-voiding no clean solder paste is available in SAC305 T4 and is a “drop-in” for most AIM no clean solder pastes. ***Eliminate voids without compromising print performance using AIM's new V9 low-voiding solder paste.***

👉 **V9 No Voids Are The Best Voids.**

Contact your AIM Representative to request your free sample today.

V9 Low-Voiding Paste

VOIDING: $\leq 1\%$



Typical Competitor Paste

VOIDING: $\geq 9\%^{+UP}$

